

Product Change Notification / CENO-02KHGL616

	Pre Change Post Change								
Pre and Post Change Summary:									
Description of Change: Qualification of MTAI as a new final test site for selected SST39LF0xx and SST39VF0xx device families available in 32L PLCC (11.5x14x3.37mm) package.									
•	Please open one of the files found te Microchip includes identical files								
PCN Type:Manufacturing (Change								
PCN Status:Final Notificati	on								
Notification Text:									
CENO-02 KHGL616_Affec CENO-02 KHGL616_Affec									
Affected CPNs:	. 1 CDV 11100000 10								
	alification of MTAI as a new final to s available in 32L PLCC (11.5x14x3	est site for selected SST39LF0xx and .37mm) package.							
Notification Subject:									
Manufacturing Change									
PCN Type:									
Memory									
Product Category:									
18-Nov-2022									
Date:									
	Todact Change Notification / CLIVO 021010L010								

Final Test Site		King Yuan Electronics Company, Limited	Microchip Technology Thailand (HQ)			
- mar reser		(KYE)	(MTAI)			
Base Quantity	Tube	30	30			
Multiple (BQM)	Tape and Reel	750	750			
	Tube	See attached Pre and Post Change Summary for comparison.				
Pin 1 Orientation	Tape and Reel	Quadrant1-2	Quadrant1-2			
Carrier Ta	ре	No changes. See attached Pre and Post Change Summary for comparison.				
Cover Ta	pe	Minor changes. See attached Pre and Post Change Summary for comparison.				
Plastic Re	el	Minor changes. See attached Pre and Post Change Summary for comparison.				
Packing Me	thod	See attached Pre and Post (See attached Pre and Post Change Summary for comparison.			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying MTAI as a new final test site.

Change Implementation Status:In Progress

Estimated First Ship Date:December 9, 2022 (date code: 2250)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2022			->	November 2022			2	December 2022						
Manlana ak	3	3	3	3	3		4	4	4	4	4		51	F 2	F 2
Workweek	2	3	4	5	6		5	6	7	8	9	50	21	52	53
Initial PCN Issue		,													
Date		Х													

Qual Report Availability					х				
Final PCN Issue Date					х				
Estimated Implementation Date							x		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN # Qual Report.

Revision History:August 8, 2022: Issued initial notification.

November 18, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 9, 2022.

Attachments:

PCN_CENO-02KHGL616_Pre and Post Change Summary.pdf PCN_CENO-02KHGL616_Qualification Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CENO-02KHGL616 - CCB 5240 Final Notice: Qualification of MTAI as a new final test site for selected SST39LF0xx and SST39VF0xx device families available in 32L PLCC (11.5x14x3.37mm) package.

Affected Catalog Part Numbers (CPN)

SST39LF040-55-4C-NHE

SST39LF020-55-4C-NHE

SST39LF010-55-4C-NHE

SST39LF040-55-4C-NHE-RVL

SST39VF040-70-4C-NHE

SST39VF020-70-4C-NHE

SST39VF010-70-4C-NHE

SST39VF040-70-4C-NHE-PP013

SST39VF040-70-4C-NHE-RVL

SST39VF040-70-4I-NHE

SST39VF020-70-4I-NHE

SST39VF010-70-4I-NHE

SST39LF040-55-4C-NHE-RVL-T

SST39VF040-70-4C-NHE-T

SST39VF020-70-4C-NHE-T

SST39VF010-70-4C-NHE-T

SST39VF040-70-4I-NHE-T

SST39VF010-70-4I-NHE-T

CCB 5240 Pre and Post Change Summary

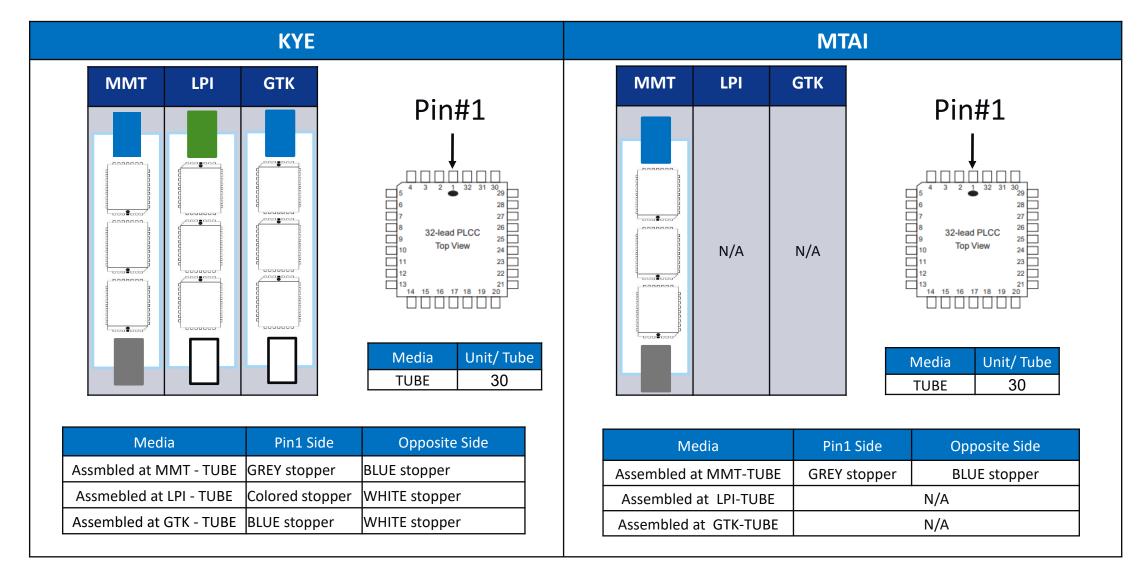
PCN #: CENO-02KHGL616



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

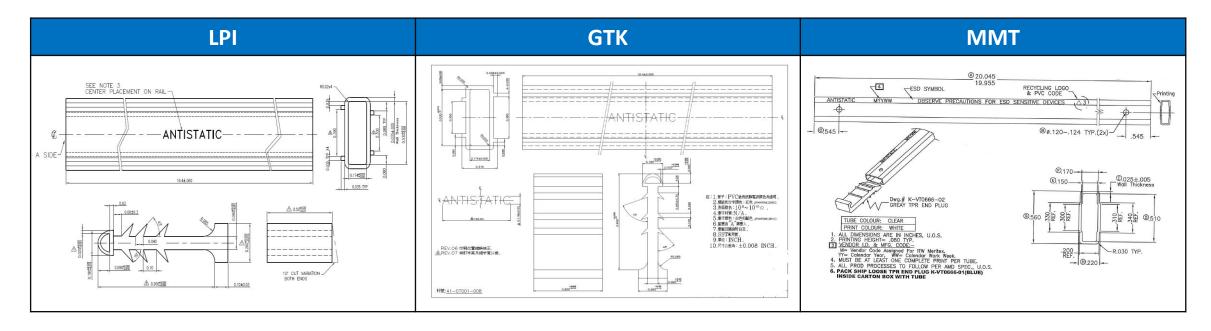


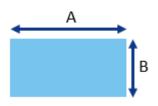
Tube – BQM and Pin 1 Orientation





Tube - Drawing





Tube	Final Test Site	Tube Length (in)	Dimension A (in)	Dimension B (in)	Tube Color
Assembled at LPI	KYE	19.4	0.53	0.174	Clear
Assembled at GTK	KYE	19.4	0.53	0.174	Clear
Assembled at MMT	KYE, MTAI	20.045	0.510	0.150	Clear



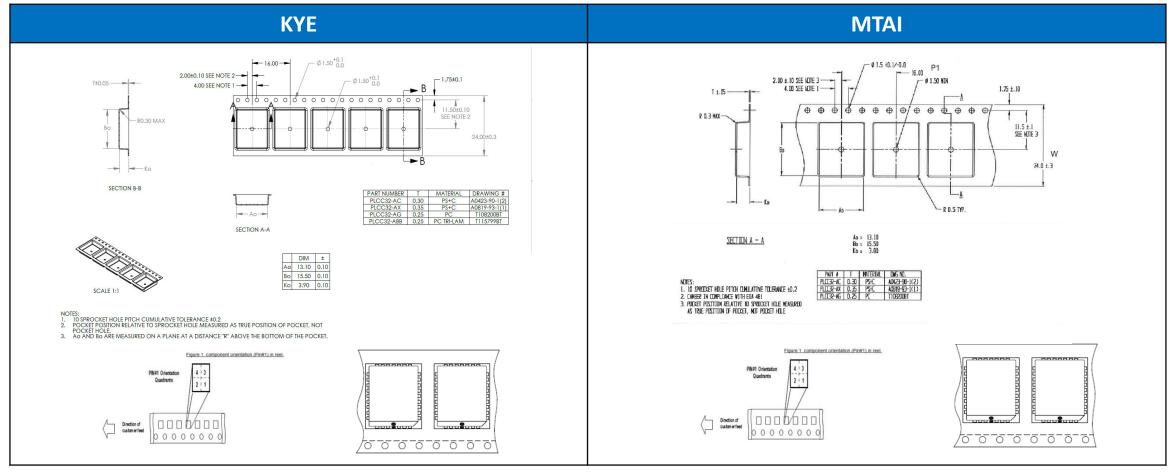
Tube - Packing Method (Dry Pack)



Plant	MSL Level	Desiccant	Humidity Indicator Card	Baking Condition
KYE	MSL-3	2 units	1 pcs	6 hours @125°C
MTAI	MSL-3	2 units	1 pcs	6 hours @125°C



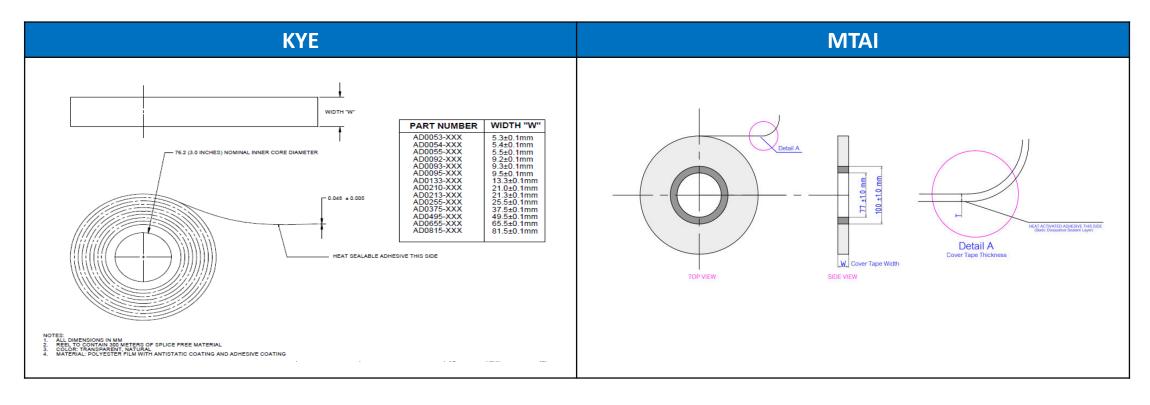
Tape and Reel – Carrier Tape



Plant	W (mm.)	P (mm.)	A0 (mm.)	B0 (mm.)	K0 (mm.)	K1 (mm.)	Thickness	BQM	Pin1
KYE	24.00 ±0.30	16.00 ±0.10	13.10 ±0.10	15.50 ±0.10	3.90 ±0.10	-	0.30 ±0.05	750	Quadrant 1-2
MTAI	24.00 ±0.30	16.00 ±0.10	13.10 ±0.10	15.50 ±0.10	3.90 ±0.10	-	0.30 ±0.50	750	Quadrant 1-2



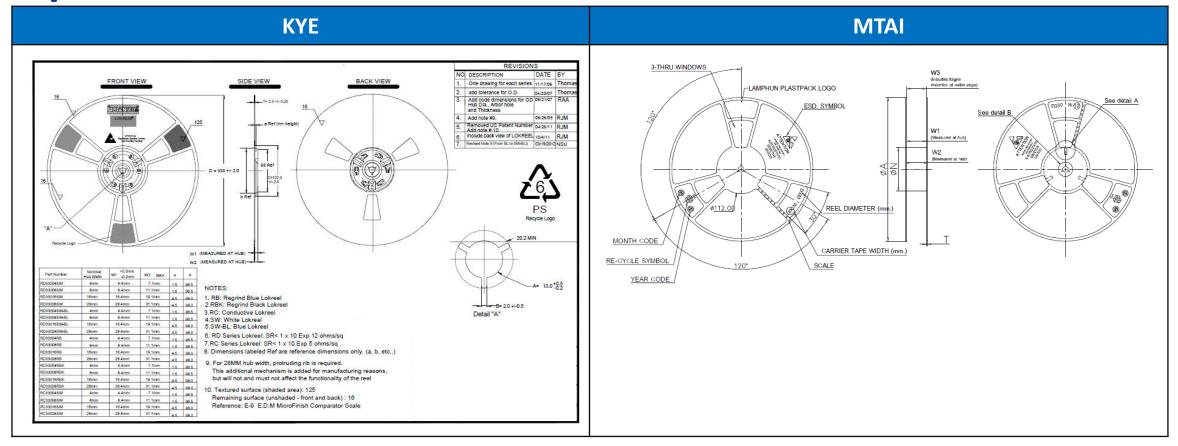
Tape and Reel – Cover Tape



Plant	Width W (mm.)	Width W (mm.) Thickness T (mm.)		Sealing Methodology	
KYE	21.3±0.1	0.048±0.005	Transparent	Heat Seal	
MTAI	21.0 ±0.1	0.050 ±0.010	Clear	Heat Seal	



Tape and Reel – Plastic Reel



Plant	Reel Diameter (mm.)	Reel Hub Size (mm)	Reel Width Max (mm.)	Color
KYE	330 ±2.0	102±2.0	8.4+16.4	Regrind Blue
MTAI	330 ±2.0	100 ±2.0	30.40	Dark Blue



Tape and Reel – Packing Method (Dry Pack)







QUALIFICATION REPORT SUMMARY RELIABILITY LABORATORY

PCN #: CENO-02KHGL616

Date

November 2, 2022

Qualification of MTAI as a new final test site for selected SST39LF0xx and SST39VF0xx device families available in 32L PLCC (11.5x14x3.37mm) package.

Purpose: Qualification of MTAI as a new final test site for selected SST39LF0xx and SST39VF0xx device families available in 32L PLCC (11.5x14x3.37mm) package.

CCB# 5240

Test	Parameters	Result
Correlation Plan	 FT: Test yield must be less than 1% delta against KYE test yield records. All correlation rejects must be verified with matching binto-bin results or with Electronic Failure Analysis (EFA) needed for justification and disposition. Approval from TE/PE based on verification (+EFA) results. QC: 100% yield All correlation rejects must be verified with matching binto-bin results or with Electronic Failure Analysis (EFA) needed for justification and disposition. Approval from TE/PE based on verification (+EFA) results. 	PASS